

# **Small Signal Diode**



#### **Features**

- ♦Meet IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- ♦Meet IEC61000-4-4 (EFT) rating. 40A (5/50ήs)
- ♦Protects one birectional I/O line
- ♦Working Voltage : 5V
- ♦Pb free version, RoHS compliant, and Halogen free

#### **Mechanical Data**

- ♦ Case : SOD-323 small outline plastic package
- →Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- ♦High temperature soldering guaranteed: 260°C/10s

→Mounting position: Any→Weight: 4.85±0.5 mg→Marking Code: 2B

### **Applications**

- ♦ Cell Phone Handsets and Accessories
- ♦Notebooks, Desktops, and Servers
- ♦Keypads, Side Keys, USB 2.0, LCD Displays
- ♦Microprocessor based equipment

#### **Ordering Information**

Part No.	Package	Packing	Packing Code	Marking
TESDC5V0	SOD-323	3K / 7" Reel	RRG	2B

## **Maximum Ratings and Electrical Characteristics**

Rating at 25°C ambient temperature unless otherwise specified.

#### Maximum Ratings

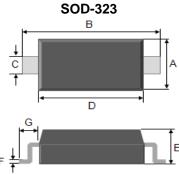
maximam radingo				
Type Number	Symbol	Value	Units	
Peak Pulse Power (tp=8/20µs waveform)	P <sub>PP</sub>	500	W	
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	Vesd	±15 ±8	KV	
Junction and Storage Temperature Range	TJ, Tstg	-55 to + 150	°C	

#### **Electrical Characteristics**

Type Number			Symbol	Min	Max	Units
Reverse Stand-Off Voltage			V <sub>RWM</sub>	-	5	V
Reverse Breakdown Volta	I <sub>R</sub> =	1mA	$V_{(BR)}$	6	=	V
Reverse Leakage Curren	V <sub>R</sub> =	5V	lR	-	5	uA
Clamping Voltage	I <sub>PP</sub> =	5A	\/o	-	9.8	\/
	I <sub>PP</sub> =	24A	Vc	=	14.5	]
Junction Capacitance	V <sub>R</sub> =0V, f=1.0MHz		Сл	200(	Тур.)	pF

Notes: 1. The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary despending on application.

# TESDC5V0 Bi-directional ESD Protection Diode

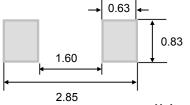


Dimensions	Unit (mm)		Unit (inch)		
Dimensions	Min	Max	Min	Max	
Α	1.20	1.40	0.047	0.055	
В	2.50	2.70	0.098	0.106	
С	0.25	0.35	0.010	0.014	
D	1.60	1.80	0.063	0.071	
E	0.80	0.90	0.031	0.035	
F	0.08	0.15	0.003	0.006	
G	0.19 REF		0.475 REF		

#### **Pin Configutation**



# **Suggested PAD Layout**



Unit: mm



# **Small Signal Diode**

# **Rating and Characteristic Curves**

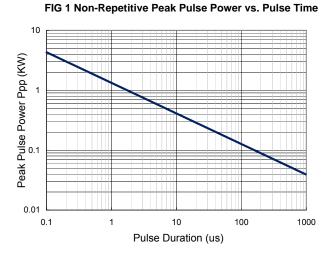


FIG 2 Pulse Waveform

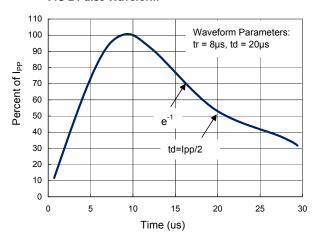
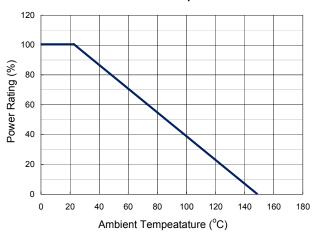


FIG 3 Admissible Power Dissipation Curve



**FIG 4 Typical Junction Capacitance** 

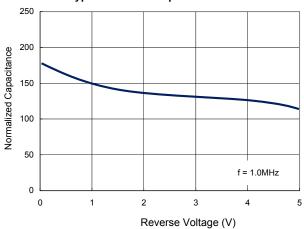
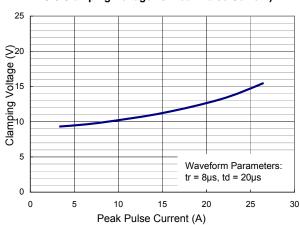


FIG 5 Clamping Voltage vs. Peak Pulse Current)





#### **Small Signal Diode**

## **Applications Information**

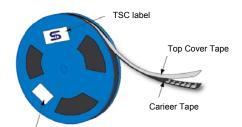
- ♦Designed to protect one data, I/O, or power supply line.
- ♦Designed to protect sensitive electronics from damage or latch-up due to ESD
- ♦Designed to replace multilayer varistors (MLVs) in portable applications
- ♦Offers superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs
- ♦The combination of small size and high ESD surge capability makes them ideal for use in portable applications.

### **Circuit Board Layout Recommendations**

Good circuit board layout is critical for the suppression of ESD induced transients.

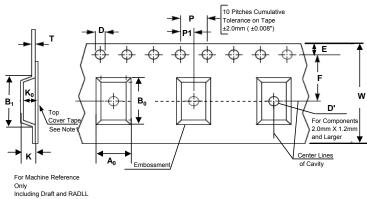
- ♦ Place the ESD Protection Diode near the input terminals or connectors to restrict transient coupling.
- ♦ Minimize the path length between the ESD Protection Diode and the protected line.
- ♦Minimize all conductive loops including power and ground loops.
- ♦The ESD transient return path to ground should be kept as short as possible.

#### **Tape & Reel specification**



Any Additional Label (If Required)

Concentric Around Bo

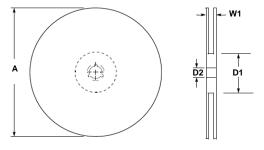


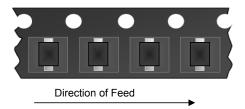
nom	Cymbol	(mm)
Carrier depth	K	2.40 Max.
Sprocket hole	D	1.50 +0.10
Reel outside diameter	Α	178 ± 1
Reel inner diameter	D1	50 Min.
Feed hole width	D2	13.0 ± 0.5
Sprocke hole position	E	1.75 ±0.10
Punch hole position	F	3.50 ±0.05
Sprocke hole pitch	P0	4.00 ±0.10
Embossment center	P1	2.00 ±0.10
Overall tape thickness	Т	0.6 Max.
Tape width	W	8.30 Max.
Reel width	W1	14.4 Max.

**Symbol** 

Item

Dimension





Note 1:  $A_{0}$ ,  $B_{0}$ , and  $K_{0}$  are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min. to 0.5 mm max. The component cannot rote more than 100 within the determined cavity.

Note 2: If B1 exceeds 4.2 mm(0.165") for 8 mm embossed tape, the tape may not feed through all tape feeders.